

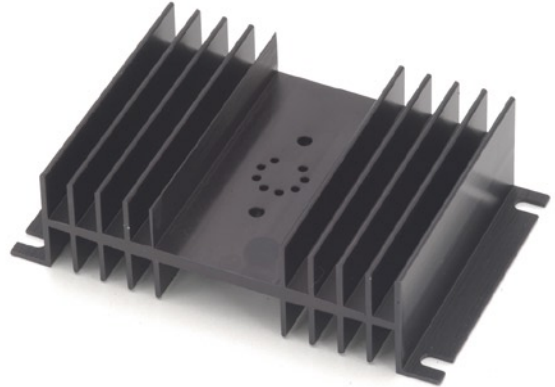
APPLICATION NOTE PA08

EVALUATION KIT

EK09 is an easy to use engineering platform for prototype evaluation. Provided items include: PC boards to make a five sided box, cage jacks and 200V ceramic bypass capacitors. The top board has pads for two TO-3 packages and one MO127 package. Two ends of the box are predrilled for banana jacks and BNC connectors (not supplied). Amplifiers and heatsinks are sold separately.

HEATSINKS

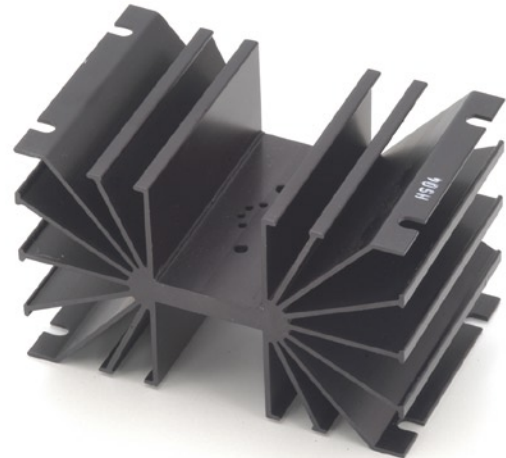
The following heatsinks are mechanically compatible with this amplifier. Thermal ratings are for optimum mounting in free air.



HS03 1.7°C/W



HS01 11.6°C/W



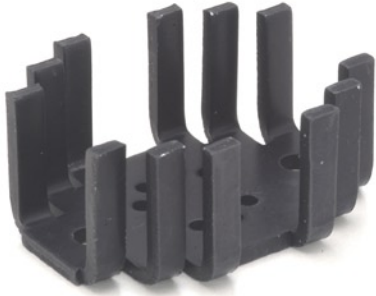
HS04 0.95°C/W



HS02 4.5°C/W



HS05 0.85°C/W



HS09 11.7°C/W



HS14 2°C/W

CAGE JACKS



HS11 0.68°C/W

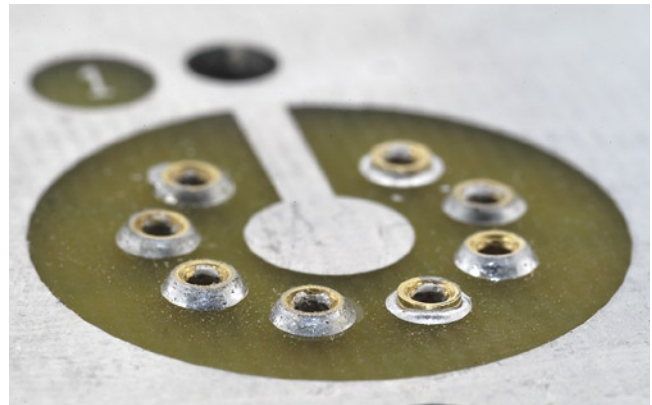
With liquid cooling the HS11 thermal rating can be reduced to .1°C/W.



MS02

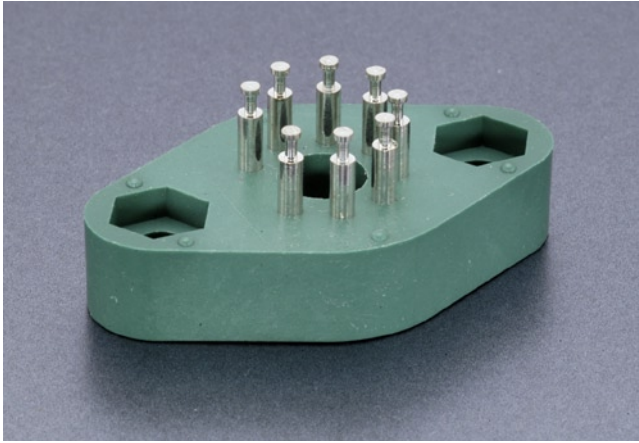


HS13 1.48°C/W



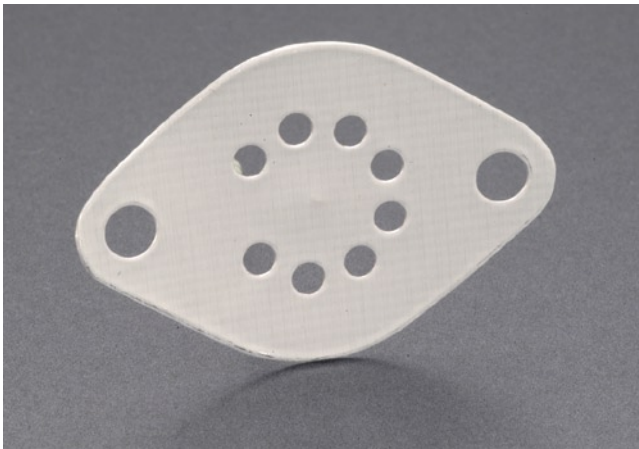
Part number MS02 consists of a package of 8 cage jacks. These are mounted directly in a print circuit board. Use a spacer between the PCB and the heatsink to avoid short circuits.

SOCKET



MS03

THERMAL WASHER



TW03

NOTES:

1. Base material is aluminum, 0.002" thick. Do not allow the washer to touch pins of the amplifier.
2. For optimum thermal transfer, avoid abrasive handling of washers which can damage their 0.5mil thick layer of thermal compound with which each side is coated.
3. The dry thermal compound will flow filling header to heatsink voids as soon as the material reached 60°C.
4. Do not store unused thermal washers above 40°C.
5. A new washer must be used for each mounting.
6. Part number TW03 consists of a package of 10 washers.
7. Thermal resistance is 0.1°C/W.